DP \$40.00 1315136

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hiroyuki KATAYAMA	05/25/2011
Takashi KONDO	05/25/2011
Hirokazu MATSUDA	05/25/2011
Ryuichi KIMURA	05/25/2011

RECEIVING PARTY DATA

Name:	NITTO DENKO CORPORATION		
Street Address:	1-2, Shimohozumi 1-chome		
Internal Address:	lbaraki-shi		
City:	Osaka		
State/Country:	JAPAN		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13151366

CORRESPONDENCE DATA

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NAME OF SUBMITTER:

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Total Attachments: 1

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501551560 REEL: 026375 FRAME: 0674

REEL: 026375 FRAME: 0675

ASSIGNMENT

Whereas, I/we Hiroyuki KATAYAMA, Takashi KONDO, Hirokazu MATSUDA and Ryuichi KIMURA, all of Osaka, Japan

hereinafter called assignor(s), have invented certain improvements in COMPOSITION FOR THERMOSETTING SILICONE RESIN and executed an application for Letters Patent of the United States of America therefor on

May 25, 2011; and

Whereas. NITTO DENKO CORPORATION of 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka, Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including the right to claim priority under 35 U.S.C. § 119, and I/we request the Director - U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignee.

I/We	hereb	y aut	horize	and reque	est my/our attorneys SUGHRUE MION, PLLC of 2100		
Pennsylvania Avenue, N.W., Washington, D.C. 20037-3213 to insert here in parentheses (Application							
number				, filed) the filing date and application		
number of said application when known.							
Date:	May	25,	2011	s/_	M. Hutayanı Hiroyuki KATAYAMA		
Date:	May	25,	2011	s/_	Takashi KONDO		
Date:	May	25,	2011	s/_	H. Matsuda. Hirokazu MATSUDA		
Date:	May	25,	2011	s/_	Ryuichi KIMURA		
Date:				s/_			

Date:

RECORDED: 06/02/2011

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §2PATENT